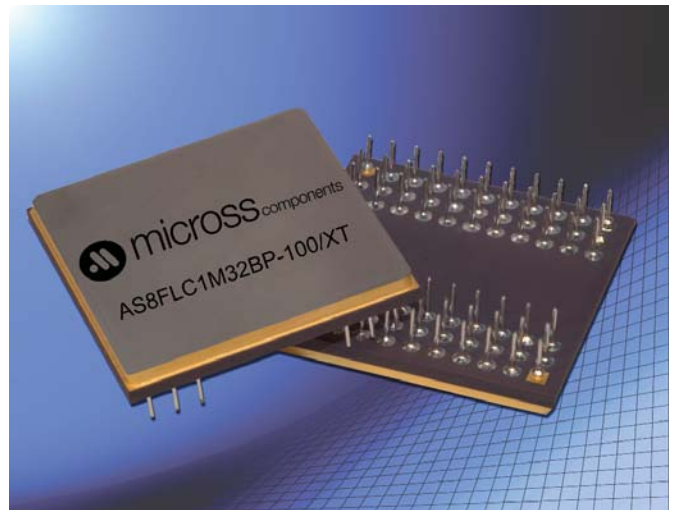


AS8FLC1M32

AS8FLC2M32

DSCC Approved 32Mb & 64Mb
3.3V Boot Block Flash Array



32Mb & 64Mb Hermetic Flash Multi-Chip Module

FEATURES

- 32Mb device, total density, organized as 1M x 32 / 64Mb device, total density, organized as 2M x 32
- Bottom boot block (sector) architecture
- Operation with single 3.3V Supply
- Available in multiple access time variations
- Individual byte control via individual byte selects (CSx\)
- Low Power CMOS
- 1,000,000 Erase/Program Cycles
- Minimum 1,000,000 Program/Erase Cycles per sector guaranteed
- Sector Architecture:
One 16K byte, two 8K byte, one 32K byte and thirty-one 64Kbyte sectors (byte mode)
- Any combination of sectors can be concurrently erased
- MCM supports full array (multi-chip) Erase
- Embedded Erase and Program Algorithms
- Erase Suspend/Resume; Supports reading data from or programming data to a sector not being Erased
- TTL Compatible Inputs and Outputs

APPLICATIONS

- Core program boot code storage
- Navigation / GPS / RADAR
- Missile control & guidance
- Automotive / industrial applications
- Weapons control & guidance

BENEFITS

- DSCC SMD 5962-09205 approved (1Mx32)
DSCC SMD 5962-08245 approved (2Mx32)
- -55C to 125C Temperature operation
- Reliable Non-Volatile High speed Memory Access <70ns
- Very Low operating(120mA max) & Std-by Power(150uA max)
- 1,000,000 Write/Erase Cycles min
- 66PGA or 68CQFP low profile Ceramic package
- Boot Block Sector Architecture

OPTIONS

Ceramic Package

- Quad Flat Pack 68 QFP
- Hex Inline Pack 66 PGA

Timing (Cycle Time)

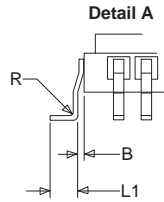
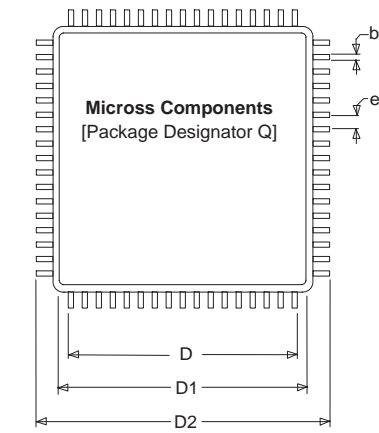
- 70ns - 120ns

Operating Temperature Ranges

- Full Military Temp (MIL-PRF-38534, Class H)
- Military Temp (-55°C to +125° C)
- Industrial Temp (-40°C to +85° C)

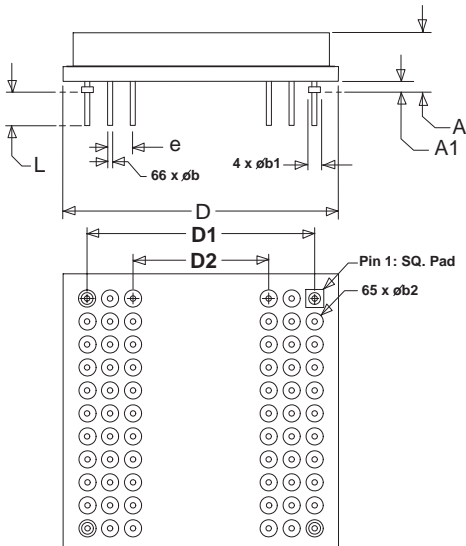
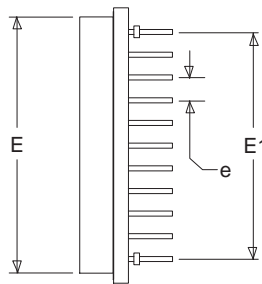
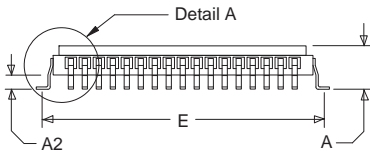
For more information or to view a complete datasheet, please visit our website at www.micross.com or call (512) 339-1188.

MECHANICAL DEFINITIONS



| Package Specifications | | |
|------------------------|-----------|-------|
| Symbol | Min | Max |
| A | 0.120 | 0.140 |
| A2 | 0.005 | 0.015 |
| B | 0.010 REF | |
| b | 0.013 | 0.017 |
| D | 0.800 BSC | |
| D1 | 0.870 | 0.890 |
| D2 | 0.980 | 1.000 |
| E | 0.936 | 0.956 |
| e | 0.050 BSC | |
| R | 0.010 TYP | |
| L1 | 0.035 | 0.045 |

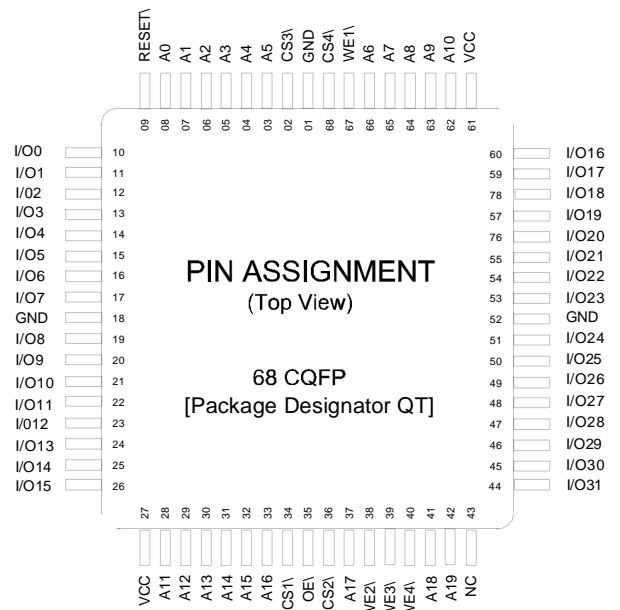
Dimensions in Inches



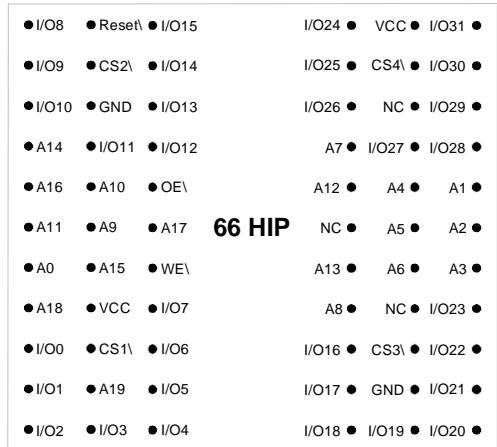
| Package Specifications | | |
|------------------------|-----------|-------|
| Symbol | Min | Max |
| A | 0.210 | 0.245 |
| A1 | 0.025 | 0.035 |
| A2 | 0.135 | 0.145 |
| øb | 0.016 | 0.020 |
| øb1 | 0.045 | 0.055 |
| øb2 | 0.065 | 0.075 |
| D/E | 1.170 | 1.200 |
| D1/E1 | 1.000 BSC | |
| D2 | 0.600 BSC | |
| D3 | 1.140 | 1.150 |
| e | 0.100 BSC | |
| L | 0.145 | 0.155 |

Dimensions in Inches

PIN ASSIGNMENT



Pin Assignment (Top View)



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